

L Number	Hits	Search Text	DB	Time stamp
11	0	6225699.URPN.	USPAT	2002/08/16 10:30
12	13	("4703483"   "5109320"   "5323060"   "5399898"   "5401672"   "5434453"   "5446247"   "5495394"   "5541449"   "5563773"   "5576519"   "5600541"   "5760478").PN.	USPAT	2002/08/16 10:31
13	28	5760478.URPN.	USPAT	2002/08/16 10:32
16	0	6291267.URPN.	USPAT	2002/08/16 10:35
17	8	("4326214"   "5307240"   "5328559"   "5383269"   "5616958"   "5760478"   "5963429"   "6084308").PN.	USPAT	2002/08/16 10:35
18	17	("5198963"   "5323060"   "5502289"   "5608262"   "5614766"   "5715144"   "5760478"   "5790384"   "5804004"   "5808878"   "5869894"   "5926379"   "5939782"   "5949135"   "5977640"   "6051886"   "6084308").PN.	USPAT	2002/08/16 10:37
19	29	5790384.URPN.	USPAT	2002/08/16 10:39
20	23	("5072364"   "5142634"   "5230068"   "5287467"   "5303356"   "5394529"   "5428786"   "5454117"   "5469551"   "5508556"   "5564118"   "5592634"   "5623614"   "5630157"   "5732278"   "5760478"   "5834835"   "5856937"   "5903908"   "5939782"   "5977640"   "5994166"   "6031284").PN.	USPAT	2002/08/16 10:43
21	12	6150724.URPN.	USPAT	2002/08/16 10:44
22	0	6339254.URPN.	USPAT	2002/08/16 10:46
23	5	("5977640"   "6127726"   "6137164"   "6147401"   "6150724").PN.	USPAT	2002/08/16 10:46
64	9898	chip adj1 chip	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/08/16 10:52
65	5010	(chip adj1 chip) and (bump ball flipchip (flip adj chip) wire wiring)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/08/16 14:47
66	3515	((chip adj1 chip) and (bump ball flipchip (flip adj chip) wire wiring)) and (substrate (printed adj circuit adj board))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/08/16 14:41
67	197	((chip adj1 chip) and (bump ball flipchip (flip adj chip) wire wiring)) and (substrate (printed adj circuit adj board))) and (second with (lager smaller))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/08/16 13:14
68	16	((chip adj1 chip) and (bump ball flipchip (flip adj chip) wire wiring)) and (substrate (printed adj circuit adj board))) and ((second adj (chip die)) with (lager smaller))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/08/16 13:35
69	181	((chip adj1 chip) and (bump ball flipchip (flip adj chip) wire wiring)) and (substrate (printed adj circuit adj board))) and (second with (lager smaller))) not (((chip adj1 chip) and (bump ball flipchip (flip adj chip) wire wiring)) and (substrate (printed adj circuit adj board))) and ((second adj chip die)) with (lager smaller)))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/08/16 13:14



70	26	(US-6246114-\$ or US-6265771-\$ or US-6208027-\$ or US-6218202-\$ or US-6225699-\$ or US-6184062-\$ or US-6150186-\$ or US-6133637-\$ or US-6037662-\$ or US-5773896-\$ or US-5977640-\$ or US-5930599-\$ or US-6369448-\$ or US-6294406-\$ or US-6291267-\$ or US-6084308-\$ or US-6215193-\$ or US-5808878-\$ or US-5790384-\$ or US-6219254-\$ or US-6204562-\$ or US-5760478-\$ or US-6150724-\$ or US-6339254-\$ or US-6147401-\$ or US-6239484-\$).did.	USPAT	2002/08/16 13:14
71	180	(((((chip adj1 chip) and (bump ball flipchip (flip adj chip) wire wiring)) and (substrate (printed adj circuit adj board))) and (second with (lager smaller))) not (((chip adj1 chip) and (bump ball flipchip (flip adj chip) wire wiring)) and (substrate (printed adj circuit adj board))) and ((second adj (chip die)) with (lager smaller)))) not ((US-6246114-\$ or US-6265771-\$ or US-6208027-\$ or US-6218202-\$ or US-6225699-\$ or US-6184062-\$ or US-6150186-\$ or US-6133637-\$ or US-6037662-\$ or US-5773896-\$ or US-5977640-\$ or US-5930599-\$ or US-6369448-\$ or US-6294406-\$ or US-6291267-\$ or US-6084308-\$ or US-6215193-\$ or US-5808878-\$ or US-5790384-\$ or US-6219254-\$ or US-6204562-\$ or US-5760478-\$ or US-6150724-\$ or US-6339254-\$ or US-6147401-\$ or US-6239484-\$).did.)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/08/16 13:25
72	2	"6225699"	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/08/16 13:25
73	3	"6333564"	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/08/16 13:25
74	1	"6414396"	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/08/16 13:26
75	1	"6400007"	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/08/16 13:26
76	7	"6225699" "6333564" "6414396" "6400007"	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/08/16 13:34
77	0	6400007.URPN.	USPAT	2002/08/16 13:27
78	7	("5804874"   "RE36613"   "6087718"   "6100594"   "6180881"   "6271598"   "6316727").PN.	USPAT	2002/08/16 13:27
79	5	6100594.URPN.	USPAT	2002/08/16 13:29
80	7	("5804874"   "RE36613"   "6087718"   "6100594"   "6180881"   "6271598"   "6316727").PN.	USPAT	2002/08/16 13:31
81	0	6333564.URPN.	USPAT	2002/08/16 13:33
82	3	("5384698"   "5521435"   "6087203").PN.	USPAT	2002/08/16 13:33
83	0	6225699.URPN.	USPAT	2002/08/16 13:33



84	3318	((chip adj1 chip) and (bump ball flipchip (flip adj chip) wire wiring)) and (substrate (printed adj circuit adj board))) not (((chip adj1 chip) and (bump ball flipchip (flip adj chip) wire wiring)) and (substrate (printed adj circuit adj board))) and (second with (lager smaller)))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/08/16 13:34
85	150	((chip adj1 chip) and (bump ball flipchip (flip adj chip) wire wiring)) and (substrate (printed adj circuit adj board))) not (((chip adj1 chip) and (bump ball flipchip (flip adj chip) wire wiring)) and (substrate (printed adj circuit adj board))) and (second with (lager smaller))) and ((second adj (chip die)) and (lager smaller))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/08/16 13:47
86	150	((chip adj1 chip) and (bump ball flipchip (flip adj chip) wire wiring)) and (substrate (printed adj circuit adj board))) not (((chip adj1 chip) and (bump ball flipchip (flip adj chip) wire wiring)) and (substrate (printed adj circuit adj board))) and (second with (lager smaller))) and (second adj (chip die)) and (lager smaller)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/08/16 13:37
87	2674	((second adj (chip die)) and (lager smaller))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/08/16 13:49
88	233	((second adj (chip die)) with (lager smaller))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/08/16 14:45
89	217	((second adj (chip die)) with (lager smaller))) not (((chip adj1 chip) and (bump ball flipchip (flip adj chip) wire wiring)) and (substrate (printed adj circuit adj board))) and (second with (lager smaller)))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/08/16 13:50
90	40	((second adj (chip die)) with (lager smaller))) not (((chip adj1 chip) and (bump ball flipchip (flip adj chip) wire wiring)) and (substrate (printed adj circuit adj board))) and (second with (lager smaller))) and (bump ball flipchip (flip adj chip))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/08/16 13:51
91	0	20020045290.URPN.	USPAT	2002/08/16 13:53
92	18	("5012323"   "5128831"   "5291061"   "5322207"   "5323060"   "5387815"   "5399898"   "5422435"   "5426566"   "5434745"   "5483024"   "5600175"   "5721452"   "5874781"   "5886412"   "5963794"   "6051886"   "6215193").PN.	USPAT	2002/08/16 13:54
93	2	6215193.URPN.	USPAT	2002/08/16 13:55
94	0	6337226.URPN.	USPAT	2002/08/16 13:56
95	2	("6215193"   "6238949").PN.	USPAT	2002/08/16 13:56
96	3	("5663106"   "6069025"   "6133637").PN.	USPAT	2002/08/16 13:56
97	3	("5663106"   "6069025"   "6133637").PN.	USPAT	2002/08/16 13:57
98	0	6337226.URPN.	USPAT	2002/08/16 13:57



99	17	("5198963"   "5323060"   "5502289"   "5608262"   "5614766"   "5715144"   "5760478"   "5790384"   "5804004"   "5808878"   "5869894"   "5926379"   "5939782"   "5949135"   "5977640"   "6051886"   "6084308").PN.	USPAT	2002/08/16 13:57
100	17	("5198963"   "5323060"   "5502289"   "5608262"   "5614766"   "5715144"   "5760478"   "5790384"   "5804004"   "5808878"   "5869894"   "5926379"   "5939782"   "5949135"   "5977640"   "6051886"   "6084308").PN.	USPAT	2002/08/16 13:59
101	3	5963794.URPN.	USPAT	2002/08/16 14:00
102	8	("4996587"   "5012323"   "5168345"   "5291061"   "5313693"   "5323060"   "5422435"   "5789805").PN.	USPAT	2002/08/16 14:04
103	10	5721452.URPN.	USPAT	2002/08/16 14:06
104	2	5959845.URPN.	USPAT	2002/08/16 14:28
105	13	("3716761"   "4613924"   "5237131"   "5258891"   "5323060"   "5490040"   "5515241"   "5541814"   "5557505"   "5721452"   "5751557"   "5754408"   "5801927").PN.	USPAT	2002/08/16 14:29
107	0	6365963.URPN.	USPAT	2002/08/16 14:32
108	3	("5808878"   "5869894"   "6181008").PN.	USPAT	2002/08/16 14:32
109	3	6181008.URPN.	USPAT	2002/08/16 14:34
110	9	("5608262"   "5635767"   "5646828"   "5808878"   "5869894"   "6150724"   "6181008"   "6201302"   "6204562").PN.	USPAT	2002/08/16 14:35
111	177	((((second adj (chip die)) with (lager smaller))) not (((chip adj1 chip) and (bump ball flipchip (flip adj chip) wire wiring)) and (substrate (printed adj circuit adj board))) and (second with (lager smaller)))) not (((second adj (chip die)) with (lager smaller))) not (((chip adj1 chip) and (bump ball flipchip (flip adj chip) wire wiring)) and (substrate (printed adj circuit adj board))) and (second with (lager smaller)))) and (bump ball flipchip (flip adj chip)))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/08/16 14:40
112	69	(((((second adj (chip die)) with (lager smaller))) not (((chip adj1 chip) and (bump ball flipchip (flip adj chip) wire wiring)) and (substrate (printed adj circuit adj board))) and (second with (lager smaller)))) not (((second adj (chip die)) with (lager smaller))) not (((chip adj1 chip) and (bump ball flipchip (flip adj chip) wire wiring)) and (substrate (printed adj circuit adj board))) and (second with (lager smaller)))) and (bump ball flipchip (flip adj chip))) and (substrate base (printed adj circuit adj board))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/08/16 14:46
113	362	((bottom lower) adj (chip die)) with (lager smaller))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/08/16 14:46



114	108	<p>(((((second adj (chip die)) with (lager smaller))) not (((chip adj1 chip) and (bump ball flipchip (flip adj chip) wire wiring)) and (substrate (printed adj circuit adj board))) and (second with (lager smaller)))) not (((second adj (chip die)) with (lager smaller))) not (((chip adj1 chip) and (bump ball flipchip (flip adj chip) wire wiring)) and (substrate (printed adj circuit adj board))) and (second with (lager smaller)))) and (bump ball flipchip (flip adj chip))) not (((second adj (chip die)) with (lager smaller))) not (((chip adj1 chip) and (bump ball flipchip (flip adj chip) wire wiring)) and (substrate (printed adj circuit adj board))) and (second with (lager smaller)))) not (((second adj (chip die)) with (lager smaller))) not (((chip adj1 chip) and (bump ball flipchip (flip adj chip) wire wiring)) and (substrate (printed adj circuit adj board))) and (second with (lager smaller)))) and (bump ball flipchip (flip adj chip))) and (substrate base (printed adj circuit adj board)))</p>	<p>USPAT; US-PGPUB; EPO; JPO; DERWENT</p>	<p>2002/08/16 14:47</p>
115	103	<p>(((bottom lower) adj (chip die)) with (lager smaller))) and (bump ball flipchip (flip adj chip) wire wiring)</p>	<p>USPAT; US-PGPUB; EPO; JPO; DERWENT</p>	<p>2002/08/16 14:48</p>
116	24	<p>(((((second adj (chip die)) with (lager smaller))) not (((chip adj1 chip) and (bump ball flipchip (flip adj chip) wire wiring)) and (substrate (printed adj circuit adj board))) and (second with (lager smaller)))) not (((second adj (chip die)) with (lager smaller))) not (((chip adj1 chip) and (bump ball flipchip (flip adj chip) wire wiring)) and (substrate (printed adj circuit adj board))) and (second with (lager smaller)))) and (bump ball flipchip (flip adj chip))) not (((second adj (chip die)) with (lager smaller))) not (((chip adj1 chip) and (bump ball flipchip (flip adj chip) wire wiring)) and (substrate (printed adj circuit adj board))) and (second with (lager smaller)))) not (((second adj (chip die)) with (lager smaller))) not (((chip adj1 chip) and (bump ball flipchip (flip adj chip) wire wiring)) and (substrate (printed adj circuit adj board))) and (second with (lager smaller)))) and (bump ball flipchip (flip adj chip))) and (substrate base (printed adj circuit adj board))) and (bump ball flipchip (flip adj chip) wire wiring)</p>	<p>USPAT; US-PGPUB; EPO; JPO; DERWENT</p>	<p>2002/08/16 14:48</p>



117	127	(((((bottom lower) adj (chip die)) with (lager smaller))) and (bump ball flipchip (flip adj chip) wire wiring)) (((((second adj (chip die)) with (lager smaller))) not (((chip adj1 chip) and (bump ball flipchip (flip adj chip) wire wiring)) and (substrate (printed adj circuit adj board))) and (second with (lager smaller))) not (((second adj (chip die)) with (lager smaller))) not (((chip adj1 chip) and (bump ball flipchip (flip adj chip) wire wiring)) and (substrate (printed adj circuit adj board))) and (second with (lager smaller))) and (bump ball flipchip (flip adj chip))) not (((second adj (chip die)) with (lager smaller))) not (((chip adj1 chip) and (bump ball flipchip (flip adj chip) wire wiring)) and (substrate (printed adj circuit adj board))) and (second with (lager smaller))) not (((second adj (chip die)) with (lager smaller))) not (((chip adj1 chip) and (bump ball flipchip (flip adj chip) wire wiring)) and (substrate (printed adj circuit adj board))) and (second with (lager smaller))) and (bump ball flipchip (flip adj chip))) and (substrate base (printed adj circuit adj board))) and (bump ball flipchip (flip adj chip) wire wiring))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/08/16 14:48
118	3	("5252179"   "6033994"   "6093331").PN.	USPAT	2002/08/16 14:54
119	9	(chip adj1 chip) and (spacer near ring)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/08/16 15:37
120	10416	spacer near ring	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/08/16 15:10
121	1	(spacer near ring) with substrate with chip	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/08/16 15:12
122	44823	support\$3 near ring	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/08/16 15:12
123	42	(support\$3 near ring) with substrate with chip	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/08/16 15:13
124	42	(support\$3 near ring) with ((pcb substrate) with chip)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/08/16 15:24
125	3	"6333564"	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/08/16 15:27
126	2932	(chip adj1 chip) and (ring surround surrounding)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/08/16 15:38
127	43	(chip adj1 chip) and (spacer with (ring surround surrounding))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/08/16 15:39
128	0	20020096785.URPN.	USPAT	2002/08/16 15:41



129	37	{"4954878"   "5099306"   "5109320"   "5128831"   "5222014"   "5239198"   "5252857"   "5291061"   "5300801"   "5323060"   "5403784"   "5422435"   "5434745"   "5466627"   "5473814"   "5477082"   "5481134"   "5494841"   "5495398"   "5496775"   "5498902"   "5498905"   "5506756"   "5508565"   "5512765"   "5512780"   "5513076"   "5535101"   "5594275"   "5612576"   "5639696"   "5705858"   "5715144"   "5728606"   "5729440"   "6051878"   "6222265") .PN.	USPAT	2002/08/16 15:46
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